

## < GaN HEMT for satellite communication (SATCOM) earth station>

# **MGFK48G2732**

Ku band internally matched power GaN HEMT 12.75 - 13.25 GHz BAND / 70W Single-carrier operable

#### DESCRIPTION

The MGFK48G2732, GaN HEMT with an N-channel schottky gate, is designed for Ku-band applications with single-carrier operation.

#### **FEATURES**

- High voltage operation
- : VDS=24V
- High output power : Po=48.3dBm (TYP.) @Pin=42dBm : PAE=33% (TYP.) @Pin=42dBm
- High efficiency
- Designed for use in Class AB linear amplifiers

#### **APPLICATION**

• Amplifier for Ku-band SATCOM

#### QUALITY

• General & Industrial

#### Packaging

Individual case

#### **RECOMMENDED BIAS CONDITIONS**

• Vds=24V • Ids=1.44A • Rg=13.3Ω

#### Absolute maximum ratings (Ta=25°C)

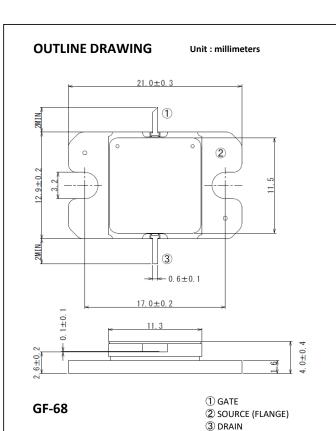
Symbol	Parameter	Ratings	Unit
Vgso	Gate to Source Voltage at Operating	-10	V
Vds	Drain to source voltage	27	V
IGF	Forward gate current	100	mA
IGR	Reverse gate current	-24	mA
τ	Screw torque	49	N∙cm
PT*1	Total power dissipation	225	W
Pin	Input power	≦44	dBm
Tch	Channel temperature	250	°C
Tstg	Storage temperature	-55 to +125	°C
Тс	Maximum case operating temperature	-10	°C

\*1:Tc=25°C

### **Recommended operating Condition**

Symbol	Parameter	Limit	Unit
Тс	Case Operating Temperature	85	°C
Vds	Drain - Source Voltage	24	V
IDQ	Drain Quiescent Current	1.44	А
Rg	Gate Resistance	13.3	Ω

#### CTHA-221214-01



## Electrical characteristics (Ta=25°C)

Parameter	Symbol	Test conditions	Limits		Unit	
			Min.	Тур.	Max.	
Pinch-off Voltage	VGS(off)	Vds=24V,ID=28.8mA	-1	-	-5	V
Output Power	Pout *2	Vds=24V,IDQ=1.44A	47.3	48.3	-	dBm
Power Added Efficiency	PAE *2	f=12.75 ,13.00, 13.25GHz *2 : Pin=42dBm *3 : Pin=27dBm *4 : Two-tone, Po=39.3dBm (Single Carrier Level) Δ f=5MHz(IM3)	-	33	-	%
Linear Power Gain	GLP *3		9	12	-	dB
3 <sup>rd</sup> Order Intermodulation distortion	IM3 *4		-	-25	-	dBc
Thermal Resistance	Rth(ch-c) *5	$\Delta$ Vf method	-	0.8	1.0	°C/W

\*5 :Channel-case

Specifications are subject to change without notice

ESD *6	Class 0	-199~
*6 :Based on EIAJ ED-4701 C-111A(C=100pF,R=1.5k $\Omega$ )		

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